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HIGH-SIDE AND LOW-SIDE GATE DRIVERS IN SO-16 (TYPE TH)
Description

The DGD2110 and DGD2113 are high-voltage / high-speed MOSFET and IGBT drivers with independent high-side and low-side outputs. The high-side driver features floating supply for operation at up to 500V/600V. The 10ns (max) / 20ns (max) propagation delay matching between the high and the low side drivers allows high-frequency operation.

The DGD2110 and DGD2113 logic inputs are compatible with standard CMOS levels (as low as 3.3V) while driver outputs feature high-pulse current buffers designed for minimum driver cross conduction.

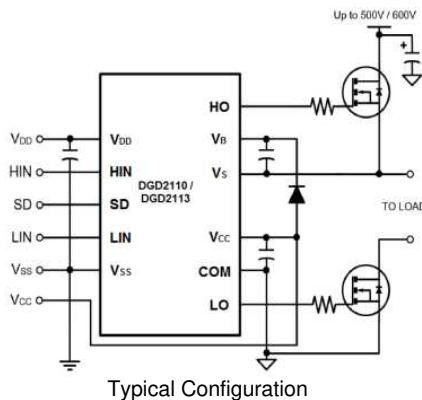
The DGD2110 and DGD2113 are offered in a 16-pin SO (Type TH) package. They operate over an extended -40°C to +125°C temperature range.

Features

- Drives two N-Channel MOSFETs or IGBTs in high-side/low-side configuration
- Floating high-side operates to 600V
- 2.5A sink / 2.5A source typical output currents
- Outputs tolerant to negative transients
- Wide gate driver supply voltage range: 10V to 20V
- Wide logic input supply voltage range: 3.3V to 20V
- Wide logic supply offset voltage range: -5V to 5V
- 15ns (typ) rise / 13ns (typ) fall times with 1000pF load
- 105ns (typ) turn-on / 94ns (typ) turn-off delay times
- Cycle-by-cycle edge-triggered shutdown circuitry
- Extended temperature range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony free. "Green" Device (Note 3)**

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers


Mechanical Data

- Case: SO-16 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.130 grams (Approximate)

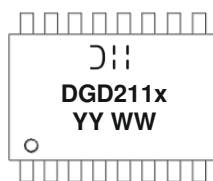


SO-16 (Type TH)
Top View

Ordering Information (Note 4)

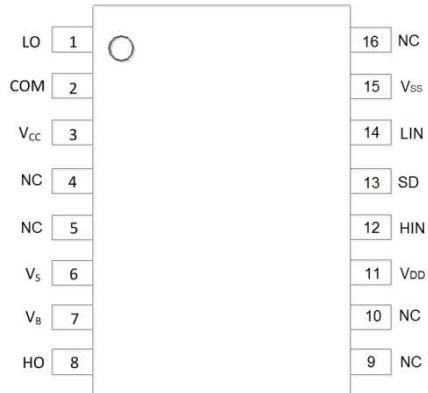
Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DGD2110S16-13	DGD2110	13	16	1,500
DGD2113S16-13	DGD2113	13	16	1,500

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


- D = Manufacturer's Marking
- DGD211x = Product Type Marking Code (See Table Above)
- YY = Year (ex: 16 = 2016)
- WW = Week (01 - 53)

Pin Diagrams

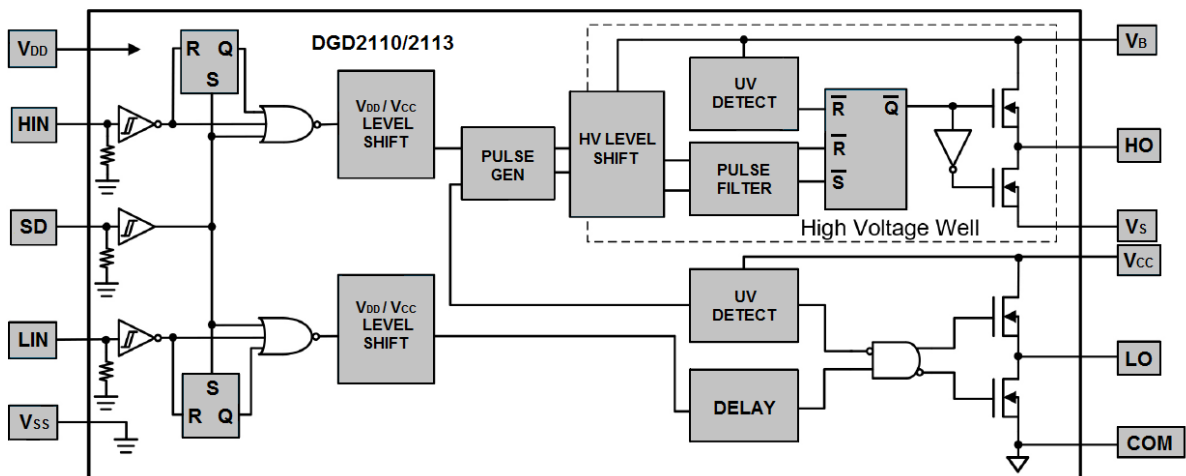


Top view: SO-16 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	LO	Low-side gate driver output pin
2	COM	Low-side gate driver power supply return pin
3	V _{CC}	Low-side gate driver power supply pin
4,5,9,10,16	NC	"No connect" pin (No Internal Connection)
6	V _S	High-side gate driver floating power supply return pin
7	V _B	High-side gate driver floating power supply pin
8	HO	High-side gate drive output pin
11	V _{DD}	Logic power supply pin
12	HIN	Logic input pin for high-side gate driver output. HIN and HO are in phase
13	SD	Logic input shutdown pin
14	LIN	Logic input pin for low-side gate driver output. LIN and LO are in phase
15	V _{SS}	Logic ground pin

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side floating supply voltage (DGD2110)	V _B	-0.3 to +524	V
High-side floating supply voltage (DGD2113)	V _B	-0.3 to +624	V
High-side floating supply offset voltage	V _S	V _B -24 to V _B +0.3	V
High-side floating output voltage	V _{HO}	V _S -0.3 to V _S +0.3	V
Offset supply voltage transient	dV _S /dt	50	V/ns
Low-side fixed supply voltage	V _{CC}	-0.3 to +24	V
Low-side output voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic supply voltage	V _{DD}	-0.3 to V _{SS} +24	V
Logic supply offset voltage	V _{SS}	V _{CC} -24 to V _{CC} +0.3	V
Logic input voltage (HIN, LIN and SD)	V _{IN}	V _{SS} -0.3 to V _{DD} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear derating factor (Note 5)	P _D	1.25	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	90	°C/W
Thermal Resistance, Junction to Case (Note 5)	R _{θJC}	45	°C/W
Operating Temperature	T _J	+150	°C
Lead Temperature (soldering, 10 seconds)	T _L	+300	
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side floating supply absolute voltage	V _B	V _S + 10	V _S + 20	V
High-side floating supply offset voltage	DGD2110 V _S	(Note 6)	500	V
High-side floating supply offset voltage	DGD2113 V _S	(Note 6)	600	V
High-side floating output voltage	V _{HO}	V _S	V _B	V
Low-side fixed supply voltage	V _{CC}	10	20	V
Low-side output voltage	V _{LO}	0	V _{CC}	V
Logic supply voltage	V _{DD}	V _{SS} + 3	V _{SS} + 20	V
Logic supply offset voltage	V _{SS}	-5 (Note 7)	5	V
Logic input voltage (HIN, LIN and SD)	V _{IN}	V _{SS}	V _{DD}	V
Ambient temperature	T _A	-40	+125	°C

Notes: 6. Logic operation for V_S = -4V to +500V. Logic state held for V_S = -4V to -V_{BS}.

7. When V_{DD} < 5V, the minimum V_{SS} offset is limited to -V_{DD}.

DC Electrical Characteristics ($V_{BIAS} (V_{CC}, V_{BS}, V_{DD}) = 15V, V_{SS} = COM, @T_A = +25^\circ C$ unless otherwise specified.) (Note 8)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" input voltage	V_{IH}	9.5	–	–	V	–
Logic "0" input voltage	V_{IL}	–	–	6.0	V	–
High level output voltage, $V_{BIAS} - V_O$	V_{OH}	–	–	1.4	V	$I_O = 0mA$
Low level output voltage, V_O	V_{OL}	–	–	0.15	V	$I_O = 20mA$
Offset supply leakage current	I_{LK}	–	–	50	μA	$V_B = V_S = 500V/600V$
Quiescent V_{BS} supply current	I_{BSQ}	–	55	230	μA	$V_{IN} = 0V$ or V_{DD}
Quiescent V_{CC} supply current	I_{CCQ}	–	56	340	μA	$V_{IN} = 0V$ or V_{DD}
Quiescent V_{DD} supply current	I_{DDQ}	–	0.6	30	μA	$V_{IN} = 0V$ or V_{DD}
Logic "1" input bias current	I_{IN+}	–	20	40	μA	$V_{IN} = V_{DD}$
Logic "0" input bias current	I_{IN-}	–	–	5.0	μA	$V_{IN} = 0V$
V_{BS} supply undervoltage positive going threshold	V_{BSUV+}	7.5	8.6	9.7	V	–
V_{BS} supply undervoltage negative going threshold	V_{BSUV-}	7.0	8.2	9.4	V	–
V_{CC} supply undervoltage positive going threshold	V_{CCUV+}	7.4	8.5	9.6	V	–
V_{CC} supply undervoltage negative going threshold	V_{CCUV-}	7.0	8.2	9.4	V	–
Output high short circuit pulsed current	I_{O+}	2.0	2.5	–	A	$V_O = 0V, V_{IN} = V_{DD}, PW \leq 10\mu s$
Output low short circuit pulsed current	I_{O-}	2.0	2.5	–	A	$V_O = 15V, V_{IN} = 0V, PW \leq 10\mu s$

Note: 8. The V_{IN} and I_{IN} parameters are referenced to V_{SS} and are applicable to all three logic input pins: HIN, LIN and SD. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics ($V_{BIAS} (V_{CC}, V_{BS}, V_{DD}) = 15V, C_L = 1000pF, V_{SS} = COM, @T_A = +25^\circ C$, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-on propagation delay	t_{ON}	–	105	150	ns	$V_S = 0V$
Turn-off propagation delay	t_{OFF}	–	94	125	ns	$V_S = 500V/600V$
Shut down propagation delay	t_{SD}	–	70	140	ns	$V_S = 500V/600V$
Turn-on rise time	t_r	–	15	35	ns	–
Turn-off fall time	t_f	–	13	25	ns	–
Delay matching	DGD2110	t_{DM}	–	10	ns	–
Delay matching	DGD2113	t_{DM}	–	20	ns	–

Timing Waveforms

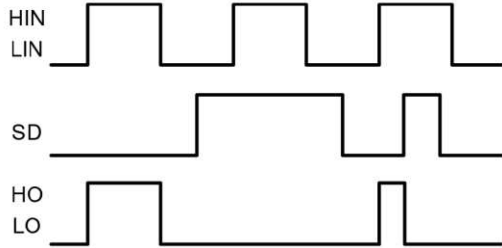


Figure 1. Input / Output Timing Diagram

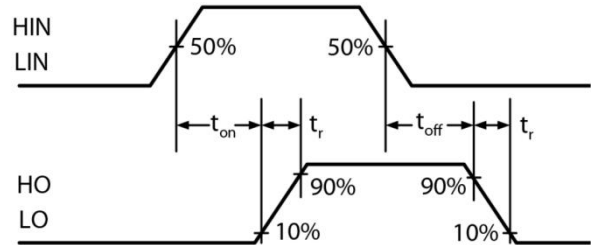


Figure 2. Switching Time Waveform Definitions

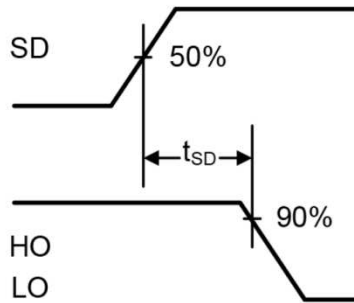


Figure 3. Shutdown Waveform Definitions

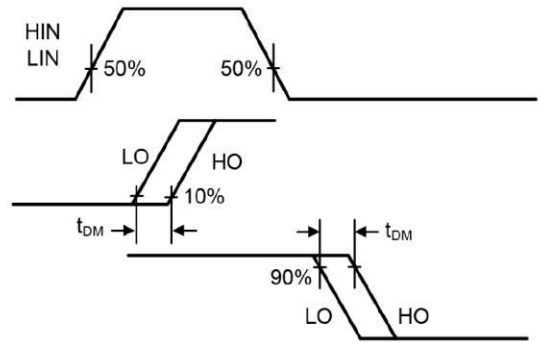


Figure 4. Delay Matching Waveform Definitions

Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

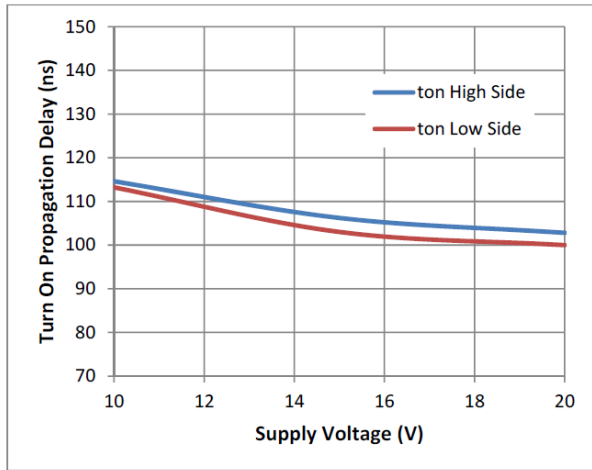


Figure 5. Turn-on Propagation Delay vs. Supply Voltage

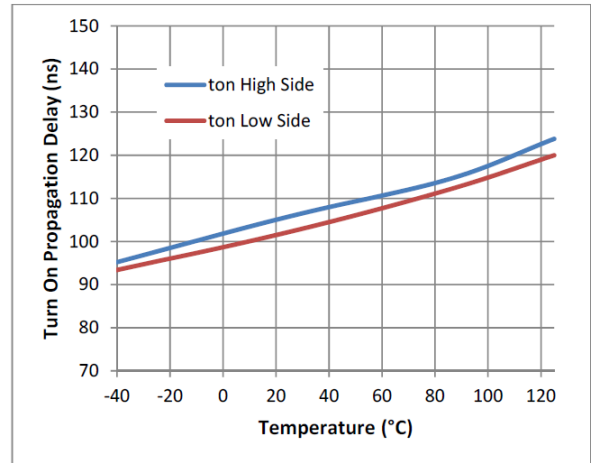


Figure 6. Turn-on Propagation Delay vs. Temperature

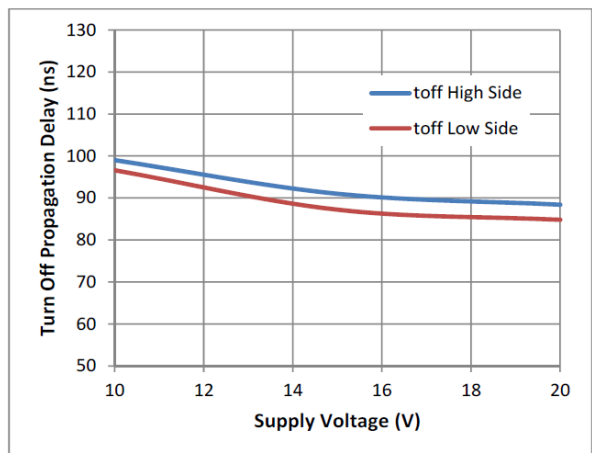


Figure 7. Turn-off Propagation Delay vs. Supply Voltage

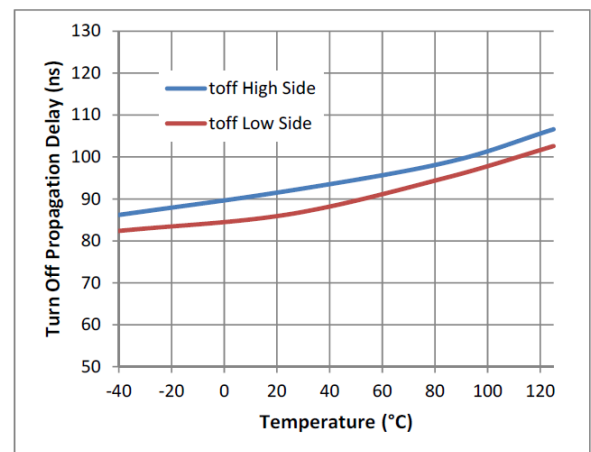


Figure 8. Turn-off Propagation Delay vs. Temperature

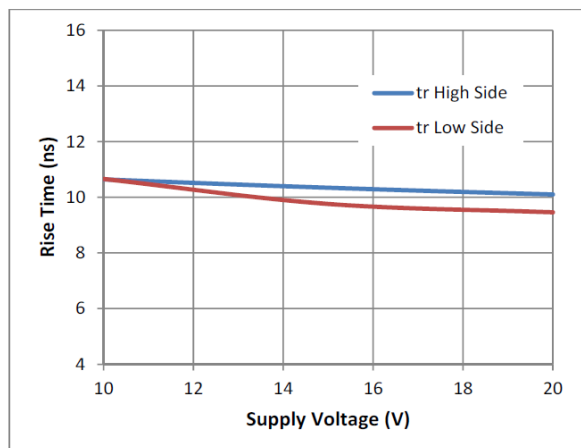


Figure 9. Rise Time vs. Supply Voltage

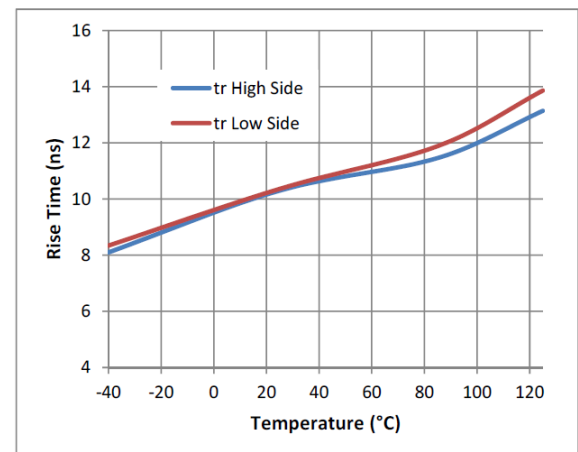


Figure 10. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

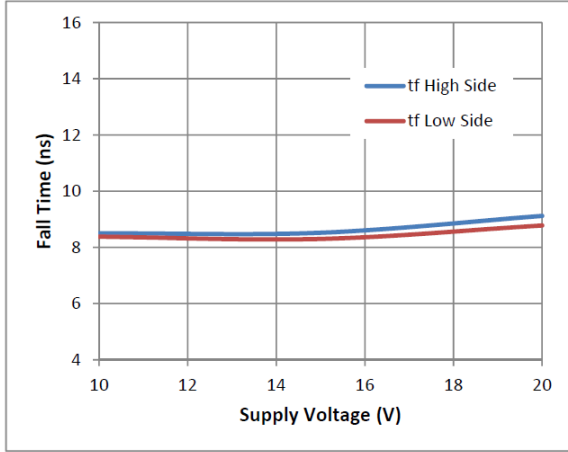


Figure 11. Fall Time vs. Supply Voltage

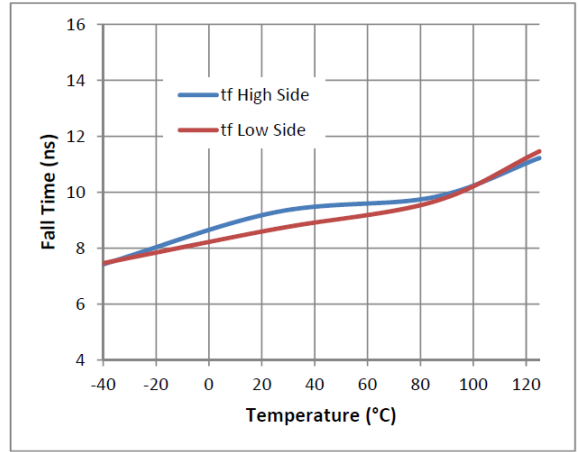


Figure 12. Fall Time vs. Temperature

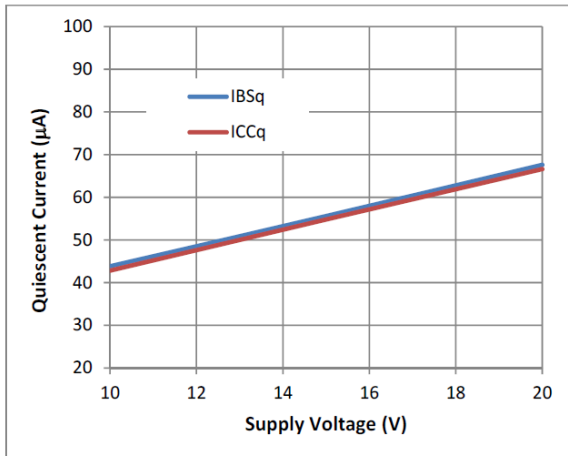


Figure 13. Quiescent Current vs. Supply Voltage

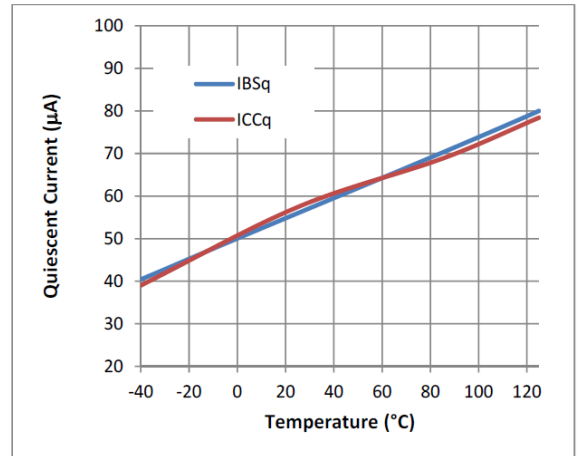


Figure 14. Quiescent Current vs. Temperature

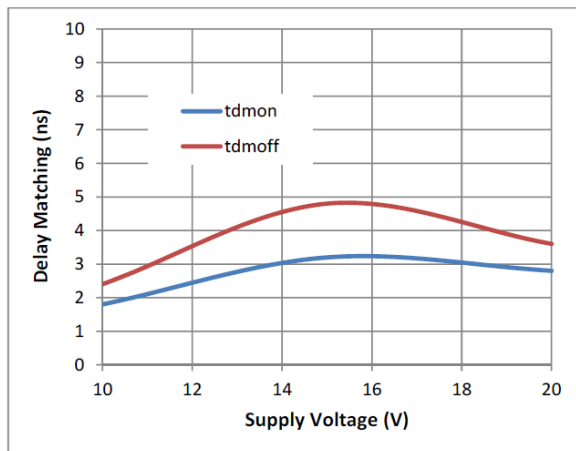


Figure 15. Delay Matching vs. Supply Voltage

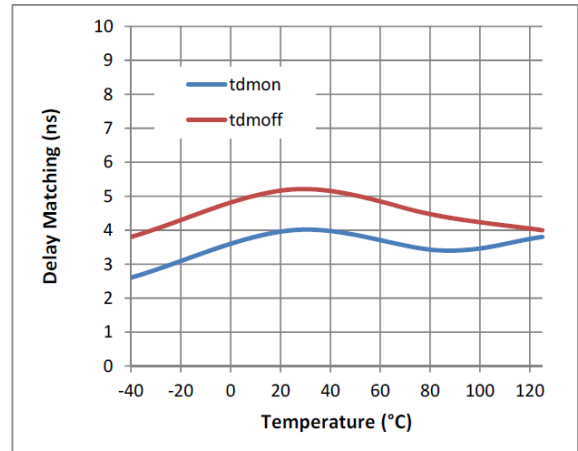


Figure 16. Delay Matching vs. Temperature

Typical Performance Characteristics (cont.)

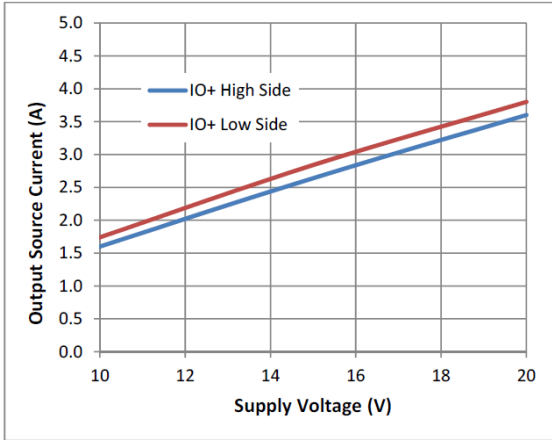


Figure 17. Output Source Current vs. Supply Voltage

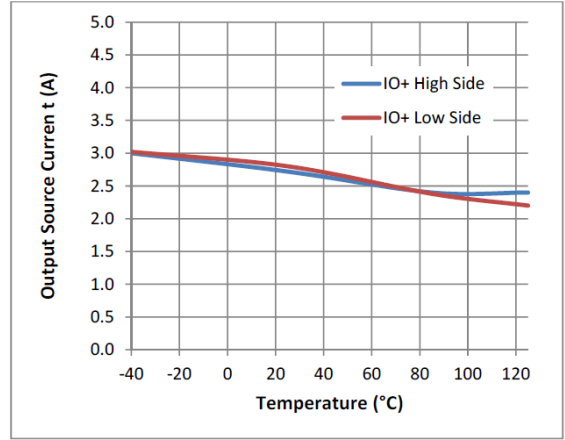


Figure 18. Output Source Current vs. Temperature

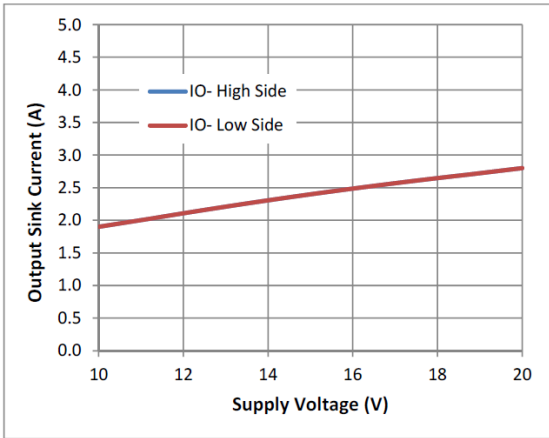


Figure 19. Output Sink Current vs. Supply Voltage

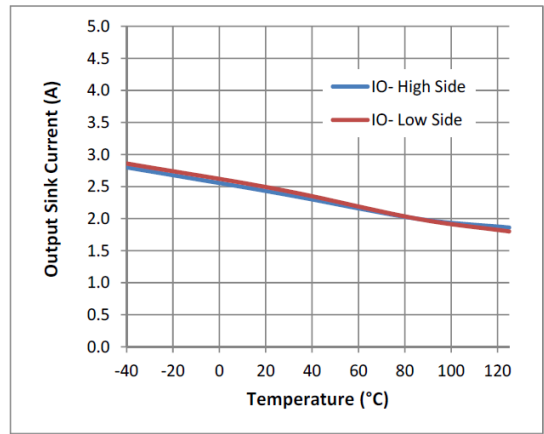


Figure 20. Output Sink Current vs. Temperature

Note: graphs overlap one another

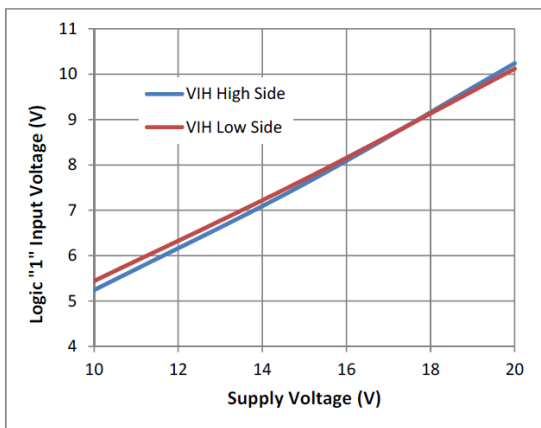


Figure 21. Logic 1 Input Voltage vs. Supply Voltage

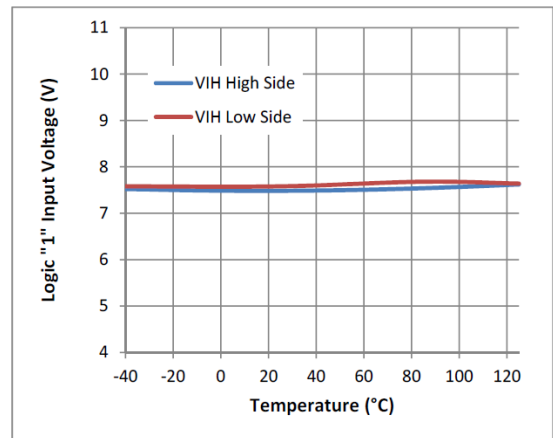


Figure 22. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (cont.)

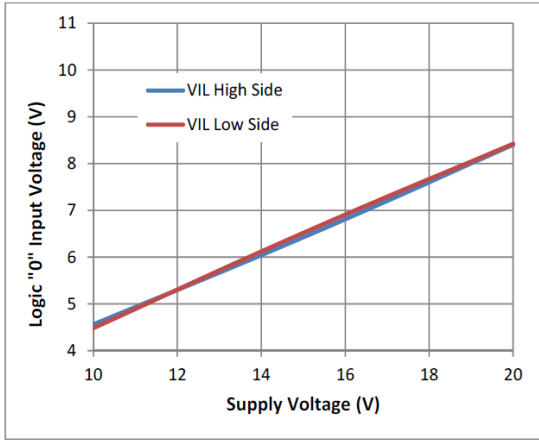


Figure 23. Logic 0 Input Voltage vs. Supply Voltage

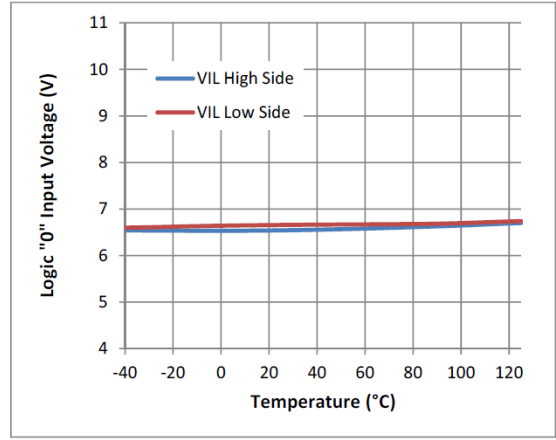


Figure 24. Logic 0 Input Voltage vs. Temperature

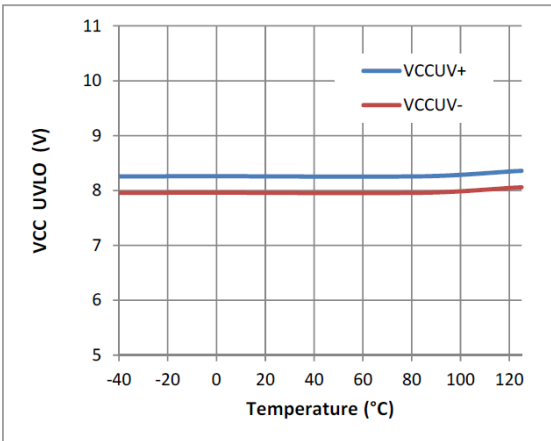


Figure 25. V_{CC} UVLO vs. Temperature

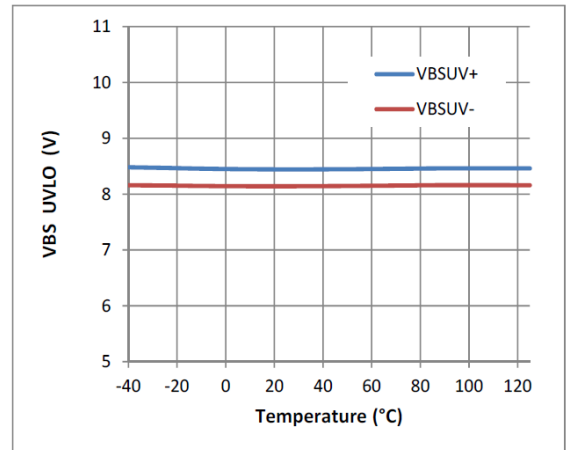


Figure 26. V_{BS} UVLO vs. Temperature

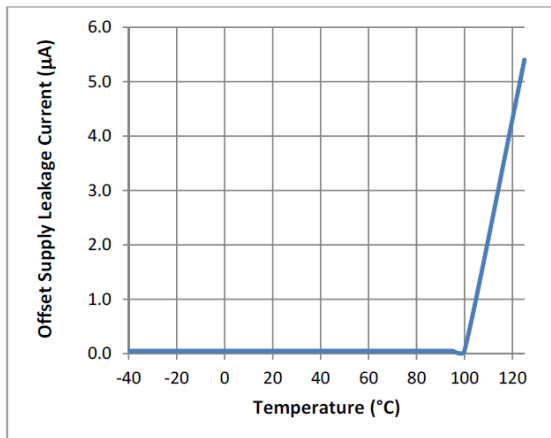


Figure 27. Offset Supply Leakage Current vs. Temperature

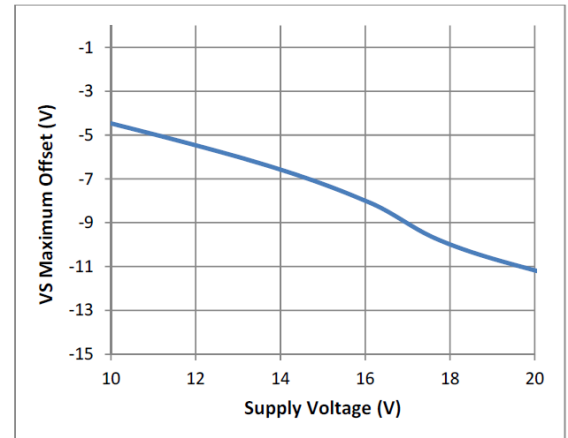


Figure 28. V_S Maximum Offset vs. Supply Voltage

Typical Performance Characteristics (cont.)

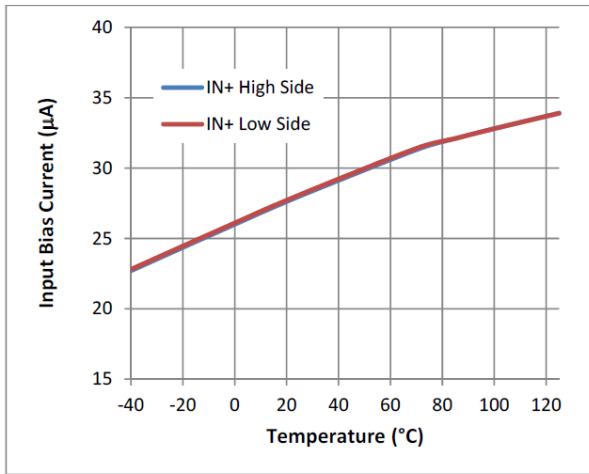
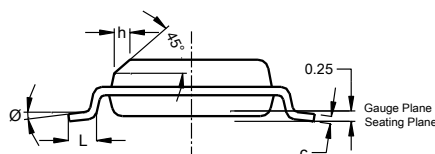
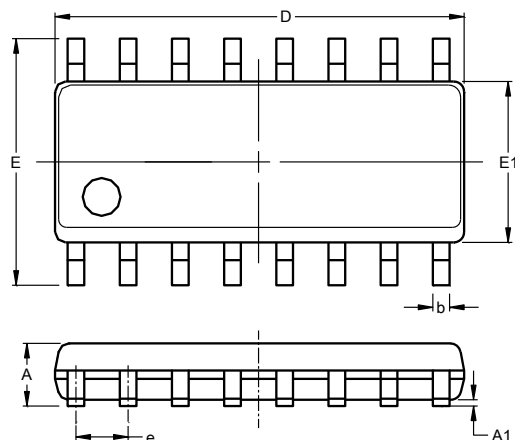


Figure 29. Input Bias Current vs. Temperature

Package Outline Dimensions

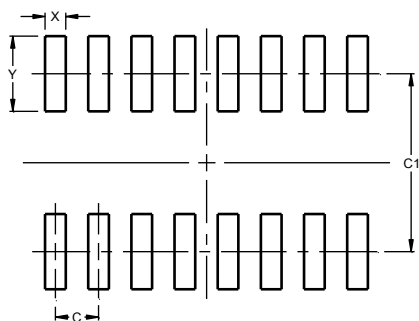
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



SO-16 (Type TH)			
Dim	Min	Max	Typ
A	2.36	2.64	--
A1	0.10	0.30	--
b	0.33	0.51	--
c	0.229	0.318	--
D	10.11	10.46	10.29
E	10.01	10.64	10.33
E1	7.42	7.59	7.52
e	--	--	1.27
h	--	--	0.48
L	0.41	1.27	--
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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